



EcoClean

Flexible Plasma Resist Strip/Descum System with Low CoO

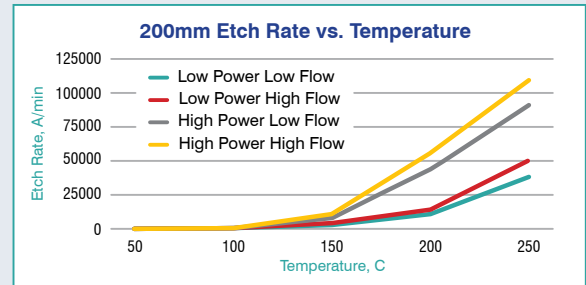


- High strip rate and high throughput
- Small footprint with single chamber
- No defects or damage due to ICP downstream plasma
- R&D to high volume production with minimal downtime
- Eco-friendly “green” process

Highly Controlled Removal Rate
 100 to 100,000 Å/min
 Up to 65 wph process
 2-5x faster,
 ½ the capital cost

Creating advanced solutions for present and next-generation technologies, the EcoClean system offers engineers flexibility and reliability for wafers:

- Photoresist removal
- PR descum
- Polyimide removal
- Organics removal
- Copper oxide removal



MEMS
 LED
 MicroLED
 Advanced Packaging
 Power Devices
 Sensors

Yield Engineering Systems (YES) has designed the EcoClean as a high throughput, low-cost of ownership, single-wafer photoresist removal system. The ICP remote source generates atomic oxygen which chemically reacts with the photoresist of the wafer surface. By employing a downstream resist strip process, high removal rate is achieved with no electrical damage or defects to the substrates and devices. EcoClean offers automated processing with low gas usage and is an eco-friendly “green” solution.

Contact Us: We offer process demonstrations. If you would like to submit samples, please call us. We can run your samples and provide a detailed process report.

Yield Engineering Systems, Inc.

Call: **1-510-954-6889** (worldwide) or **1-888-YES-3637** (US toll free)

www.yieldengineering.com



EcoClean

SPECIFICATIONS

	SPECIFICATIONS	REMARKS
PERFORMANCE	Descum Specifications	
	Approx. Ash Rate	100-1000 Å/min
	Uniformity	Within wafer: $\leq \pm 10\%$
	Photoresist Strip Rate	
	Strip Rate	$\geq 5 \mu\text{m}/\text{min}$ Temperature and photo resist dependent $\geq 10 \mu\text{m}/\text{min}$ @250C
	Uniformity	Within wafer: $\leq \pm 10\%$
HARDWARE	Wafer Per Month	At least $\geq 20\text{K}$ / month The process time including load and unload
	Wafer Temperature Range	75° to 300° C
	WiW temp Uniformity	$\pm 1.5\%$ 5 point TC wafer measured at 200° C
	Capacity	Single wafer/50mm-150mm Capable of up to 200mm wafer
	Process Gas Inputs	2 MFCs standard (Oxygen and Nitrogen), 3rd forming gas MFC optional
	O2 MFC	2000 sccm
	N2 MFC	200 sccm
	Base Pressure	≤ 50 mTorr With 350cfm Ebara Dry Pump (EV-S100)
	Leak Rate	≤ 20 mTorr/min
	RF Power	500W - 3000W
SOFTWARE	User Interface	PC with touch screen monitor and pull-out keyboard, barcode reader
	SECS/GEM	Optional
	Operating System	Windows 7 Currently supports wired Ethernet communication

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